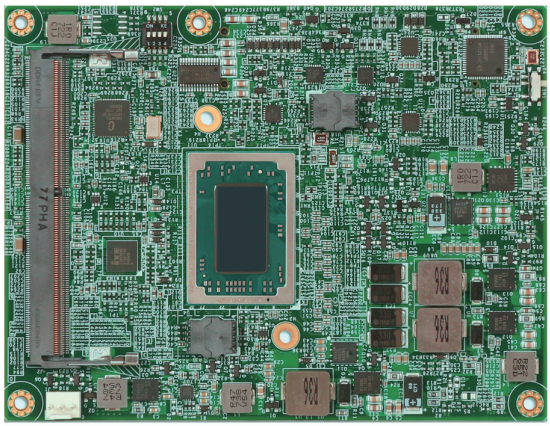
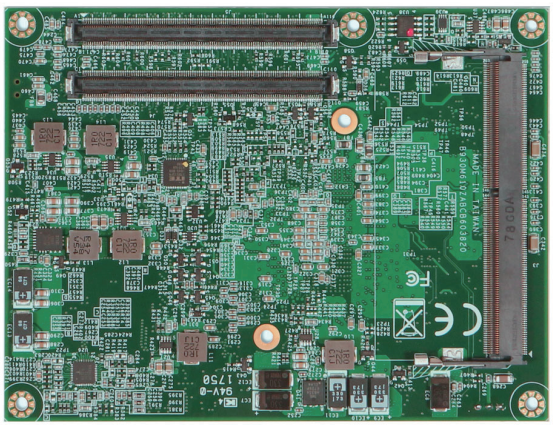
MEDM-B603

AMD Embedded V-series based on Type VI Basic COM Express 2.0 module with dual channel DDR4 SO-DIMM slots, DDI Interface, Dual Gigabit Ethernet, PCIe, SATA and USB





MEDWEL MEDM-B603 is designed with AMD next generation V-Series SoC solution which leading 3D graphics performance and high-perfromace Ryzen CPU core for the medical healthcare systems.

FEATURES

- COM Express type 6, basic form factor
- Up to 4 Ryzen Cores, AMD Radeon™ GCN Compute Units
- Support Dual Channel ECC DDR4 SO-DIMM Horizontal Socket (Up to 16GB)
- Support Four 4K Displays
- Support USB 2.0/3.0, SATA, 1 PCIe x8 and 4 PCIex1
- Next-Generation AMD Secure Processor

Form Factor

Form Factor	COM Express Type 6 Module

General

Processor	AMD Ryzen V-series
BIOS	AMI BIOS, UEFI Architecture
System Memory	Dual Channel DDR4 SO-DIMM Horizontal Socket (Up to 16GB)
Storage Device	2x SATAIII
Watchdog Timer	Programmable via S/W from 1 sec ~ 255 min
Hardware Monitoring	I2C control
Expansion Interface	- 1x PCIe x8 Interface from SoC chip - 1x PCIe x4 Interface from SoC chip

I/O Interface

Audio	High Definition Audio Interface
USB	- 2x USB 2.0 - 4x USB 3.0

Display

Graphic Controller	AMD Radeon™ GFX9 with up to 11 compute units
Display Interface	- 2x DDI - Dual Displays Support (DP/eDP/LVDS/HDMI/VGA)

Mechanical& Environmental

Dimension	125 mm x 95 mm (4.92" x 3.74")
Environment	- Operating temperature: 0°C ~ 60°C with passive cooling - Storage Temperature: -40°C ~ 85°C - Operation Humidity: 5% ~ 95%, non-condensing - RoHS compliant
MTBF	Over 120,000 hours at 40°C
EMI Certification	CE, FCC Class B